

**Sealed Choke Coil SDEB12101T MSD type**

■ **Features**

Low profile : 1.25mm x 1.00mm x 1.00mm

Low coil resistance with large currents.

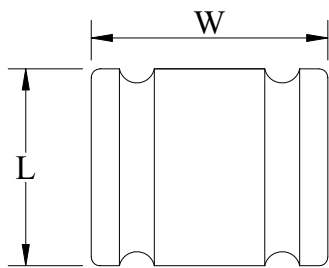
High magnetic shield construction should actualize high resolution for EMC protection.

100% lead (Pb) free meet RoHS standard

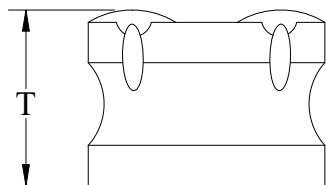
■ **Application**

Cellular phones, LCD displays, HDDs, DVCs, DSCs, PDAs etc..

■ **Outline Dimensions**



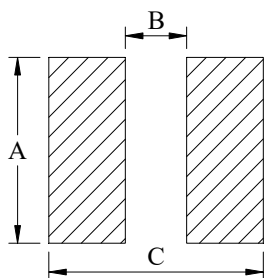
Code	Dimensions (mm)
L	1.00 ± 0.20
W	1.25 ± 0.20
T	1.0 Max.



Note : This graph is in regard to outline dimensions spec. For outer appearance, please refer to actual product.

■ **Recommend Land Pattern Dimensions**

The customer shall determine the land dimensions shown below after confirming and safety.



A	1.2
B	0.4
C	1.4

Unit : mm

### ■ Specifications

Part Number	L0 Inductance ( $\mu\text{H}$ ) @ (0A)	$R_{dc}$ (m $\Omega$ )		Heat Rating Current DC Amps. Idc (A)		Saturation Current DC Amps. Isat (A)	
		Typical	Maximum	Typical	Maximum	Typical	Maximum
SDEB12101T-R22MSD	0.22	50	60	1.90	1.71	2.40	2.16
SDEB12101T-R33MSD	0.33	66	80	1.70	1.53	2.10	1.90
SDEB12101T-R47MSD	0.47	80	96	1.55	1.40	1.55	1.40
SDEB12101T-1R0MSD	1.0	167	201	1.05	0.95	1.15	1.04
SDEB12101T-1R5MSD	1.5	230	276	0.90	0.81	0.82	0.74
SDEB12101T-2R2MSD	2.2	281	338	0.83	0.75	0.68	0.61
SDEB12101T-3R3MSD	3.3	430	516	0.58	0.52	0.52	0.47
SDEB12101T-4R7MSD	4.7	623	748	0.48	0.43	0.46	0.41
SDEB12101T-100MSD	10.0	1250	1500	0.36	0.32	0.35	0.32

\* : If you require another part number please contact with us.

\*\* : Inductance Tolerance  $\pm 20\%$

Note 1. : All test data is referenced to 25 $^{\circ}\text{C}$  ambient.

Note 2. : Test Condition: 1MHz, 1.0Vrms

Note 3. : Idc : DC current (A) that will cause an approximate  $\Delta T$  of 40 $^{\circ}\text{C}$

Note 4. : Isat : DC current (A) that will cause L0 to drop approximately 30%

Note 5. : Operating Temperature Range -55 $^{\circ}\text{C}$  to +125 $^{\circ}\text{C}$

Note 6. : The part temperature (ambient + temp rise) should not exceed 125 $^{\circ}\text{C}$  under the worst case operating conditions. Circuit design, component placement, PCB trace size and thickness, airflow and other cooling provision all affect the part temperature. Part temperature should be verified in the end application.

Note 7. : The rated current as listed is either the saturation current or the heating current depending on which value is lower.

### Current Characteristic

